

CLAIM AMENDMENTS

Please cancel claims 41-53 as shown below.

1-20. (Canceled)

21. (Previously Presented) A diamond tool formed by the process comprising the steps of:

- a) providing a mold having a diamond interface surface configuration which inversely corresponds to a desired shape for a working surface of the tool;
- b) coating said diamond interface surface with diamond using a chemical vapor deposition technique to form a diamond layer;
- c) separating the mold from the diamond layer such that the resultant diamond layer has a working surface which inversely corresponds to the diamond interface surface configuration of the mold and a growth surface opposite the working surface; and
- d) forming a tool body against at least a portion of the growth surface of the diamond layer.

22. (Original) The diamond tool of claim 21, wherein said mold comprises a metal material.

23. (Original) The diamond tool of claim 22, wherein said metal material is a member selected from the group consisting of tungsten, molybdenum, tantalum, zirconium, vanadium, chromium, carbides thereof, copper, and mixtures thereof.

24. (Original) The diamond tool of claim 21, wherein said diamond interface surface is

smooth.

25. (Original) The diamond tool of claim 21, wherein said diamond interface surface is rough.

26. (Original) The diamond tool of claim 21, wherein said diamond interface surface has a concave configuration.

27. (Original) The diamond tool of claim 21, wherein said diamond interface surface has a convex configuration.

28. (Original) The diamond tool of claim 21, wherein said diamond interface surface configuration inversely corresponds to the shape of a drawing die.

29. (Original) The diamond tool of claim 28, wherein said drawing die has a channel with a non-spherical shape.

30. (Original) The diamond tool of claim 21, wherein said diamond interface surface configuration inversely corresponds to the shape of a chemical mechanical polishing (CMP) pad dresser.

31. (Original) The diamond tool of claim 21, wherein said diamond interface surface configuration inversely corresponds to the shape of a pipe.

32. (Original) The diamond tool of claim 21, wherein said diamond interface surface configuration inversely corresponds to the shape of a diaphragm.

33. (Original) The diamond tool of claim 21, wherein said diamond interface surface configuration inversely corresponds to the shape of a cutting element.

34. (Original) The diamond tool of claim 33, wherein said cutting element contains chip breakers.

35. (Original) The diamond tool of claim 21, wherein said diamond layer has a thickness of from about 20 microns to about 200 microns.

36. (Original) The diamond tool of claim 21, further comprising the step of increasing the thickness of said diamond layer to a desired thickness, using a non-chemical vapor deposition process.

37. (Original) The diamond tool of claim 21, wherein said CVD technique is a member selected from the group consisting of: hot filament, microwave plasma, oxyacetylene flame, and arc jet techniques.

38. (Original) The diamond tool of claim 37, wherein said CVD technique utilizes a combination of methane and hydrogen gasses.

39. (Original) The diamond tool of claim 21, wherein step c) is accomplished by

chemically removing the mold from the diamond layer.

40-64. (Canceled)